

Product Change Notification - JAON-27BVIQ372

Date: 13 Mar 2018
Product Category: 8-bit PIC Microcontrollers; Capacitive Touch Sensors
Notification subject: CCB 2966.001 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package using gold (Au) bond wire.

Notification text:

PCN Status:
Final notification

PCN Type:
Manufacturing Change

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of MTAI as a new assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package using gold (Au) bond wire.

Pre Change:
Assembled at ANAC assembly site with punched singulation method using 8290 die attach material.

Post Change:
Assembled at MTAI Assembly site with sawn singulation method using 3280 die attach material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Amkor Assembly & Test (Shanghai) Co., LTD (ANAC)	Microchip Technology Thailand – HQ (MTAI)
Wire material	Au	Au
Die attach material	8290	3280
Molding compound material	G700	G700
Lead frame material	C194	C194
Singulation method	Punched	Sawn

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve productivity by qualifying MTAI assembly site with sawn singulation method.

Change Implementation Status:
In Progress

Estimated First Ship Date:
April 12, 2018 (date code: 1815)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	March 2018					April 2018				
	09	10	11	12	13	14	15	16	17	
Qual Report Availability			X							
Final PCN Issue Date			X							
Estimated Implementation Date							X			

Method to Identify Change:
Traceability code

Qualification Report:
Please open the attachments included with this PCN labeled as PCN_#_Qual Report.

Revision History:
March 13, 2018: Issued final notification. This PCN is qualified by similarity (QBS) to PCN # **KSRA-14COLN193**.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s): [PCN_JAON-27BVIQ372_Qual Report.pdf](#)
[PCN_JAON-27BVIQ372_Affected_CPN.pdf](#)
[PCN_JAON-27BVIQ372_Affected_CPN.xlsx](#)

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Affected Catalog Part Numbers (CPN)

PCN_JAON-27BVIQ372
CATALOG_PART_NBR
ATMEGA8L-8MUA4
ATMEGA8L-8MURA3
ATMEGA48V-10MURA3
ATMEGA48V-10MURA3
ATMEGA88V-10MURA1
ATMEGA48V-10MURA3
ATMEGA88V-10MURA1
QT60240-ISG
QT60160-ISG
ATMEGA88PA-MN
ATMEGA168PA-MN
ATMEGA168PA-MN
ATTINY28V-1MU
ATTINY28L-4MU
ATMEGA48A-MU
ATMEGA48A-MU
ATMEGA8L-8MURA5
ATMEGA168PA-MUA1
ATMEGA168PA-MUA1
ATTINY261A-MFR
ATMEGA48PA-MURA5
ATMEGA168PA-MURA1
ATMEGA168PA-MURA1
ATMEGA48A-MUR
ATTINY828-MUR
ATMEGA88PA-MNR
ATTINY261A-MF
ATTINY828-MU
ATMEGA48PA-MNR
ATMEGA48P-20MUR
ATMEGA88-20MUR
AT42QT1245-MUR
AT42QT1244-MUR
AT42QT1245-MU
ATMEGA168PA-MNR
ATTINY461-20MUR486
ATMEGA88PA-MURA6
ATTINY26-16MQR
ATTINY26-16MQRA3
ATMEGA48V-10MUR
ATMEGA48PA-MURA5